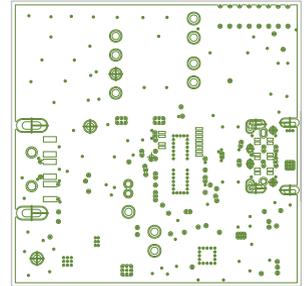
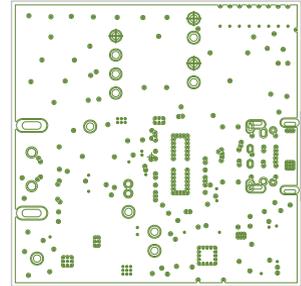


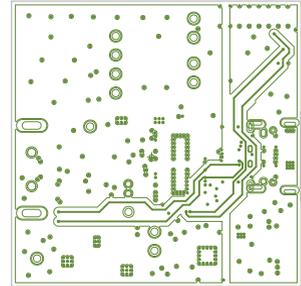
	BOARD NAME: 2522DFPDONGLE	BOARD REV: 1.0	KSID: 15428	JOB NUMBER: 124636
	ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION: LAYER 1 - TOP		



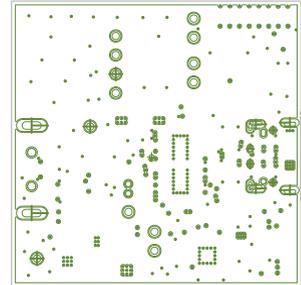
	BOARD NAME: 2522DFPDONGLE	BOARD REV: 1.0	KSID: 15428	JOB NUMBER: 124636
	ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION: LAYER 2 - GND		



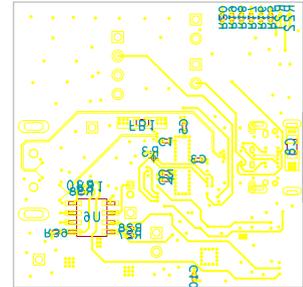
	BOARD NAME: 2522DFPDONGLE	BOARD REV: 1.0	KSID: 15428	JOB NUMBER: 124636
	ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION: LAYER 3 - PWR		



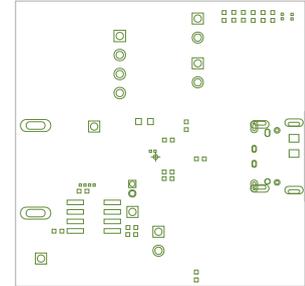
	BOARD NAME: 2522DFPDONGLE	BOARD REV: 1.0	KSID: 15428	JOB NUMBER: 124636
	ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION: LAYER 4 - PWR		



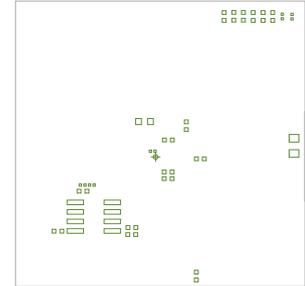
	BOARD NAME: 2522DFPDONGLE	BOARD REV: 1.0	KSID: 15428	JOB NUMBER: 124636
	ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION: LAYER 5 - GND		



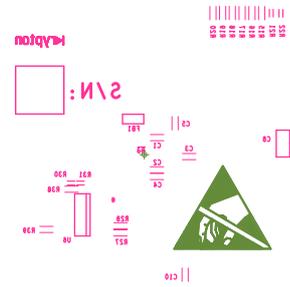
	BOARD NAME: 2522DFPDONGLE	BOARD REV: 1.0	KSID: 15428	JOB NUMBER: 124636
	ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION: LAYER 6 - BOTTOM		



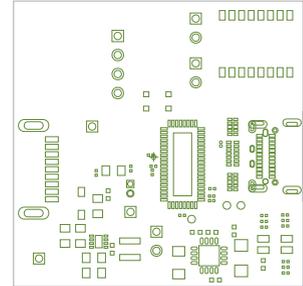
	BOARD NAME: 2522DFPDONGLE	BOARD REV: 1.0	KSID: 15428	JOB NUMBER: 124636
	ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION: LAYER 8 - SOLDERMASK BOTTOM		



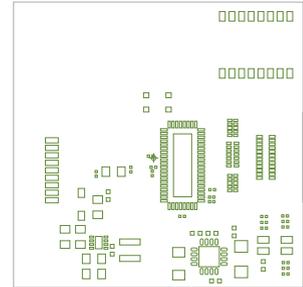
	BOARD NAME: 2522DFPDONGLE	BOARD REV: 1.0	KSID: 15428	JOB NUMBER: 124636
	ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION: LAYER 10 - PASTEMASK BOTTOM		



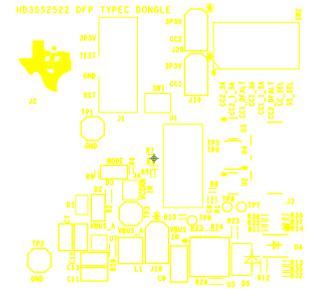
	BOARD NAME: 2522DFPDONGLE	BOARD REV: 1.0	KSID: 15428	JOB NUMBER: 124636
	ALL ARTWORK LAYERS VIEWED FROM TOP		LAYER DESCRIPTION: LAYER 12 - SILKSCREEN BOTTOM	



	BOARD NAME: 2522DFPDONGLE	BOARD REV: 1.0	KSID: 15428	JOB NUMBER: 124636
	ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION: LAYER 7 - SOLDERMASK TOP		



	BOARD NAME: 2522DFPDONGLE	BOARD REV: 1.0	KSID: 15428	JOB NUMBER: 124636
	ALL ARTWORK LAYERS VIEWED FROM TOP		LAYER DESCRIPTION: LAYER 9 - PASTEMASK TOP	



krypton
solutions

BOARD NAME:
2522DFPDONGLE

BOARD REV:
1.0

KSID:
15428

JOB NUMBER:
124636

ALL ARTWORK LAYERS VIEWED FROM TOP

LAYER DESCRIPTION:

LAYER 11 - SILKSCREEN TOP

GENERAL NOTES, UNLESS OTHERWISE SPECIFIED

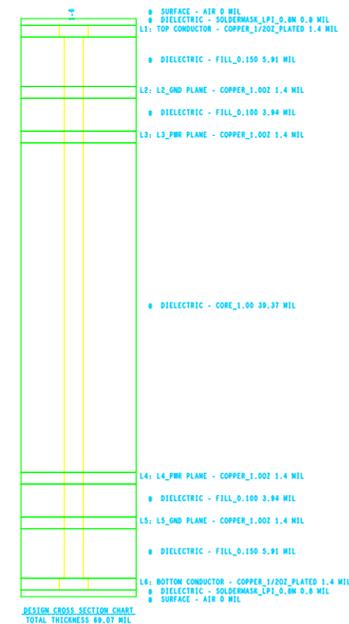
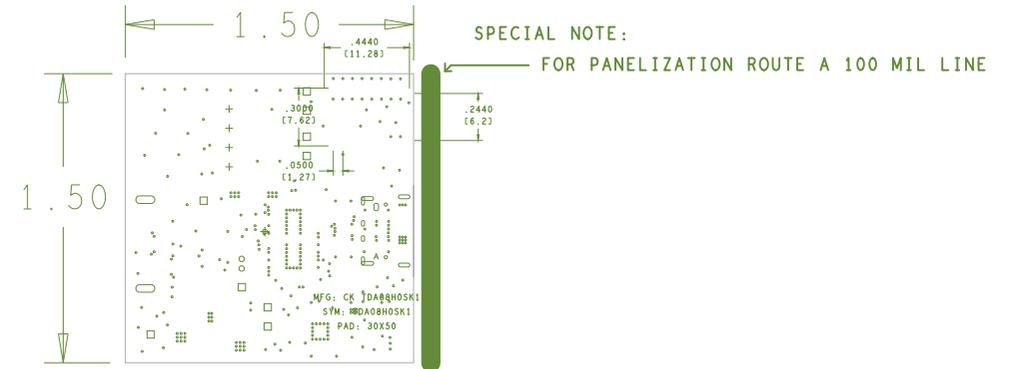
1. ALL FABRICATION ITEMS MUST MEET OR EXCEED BEST INDUSTRY PRACTICE : IPC-A-600C (Commercial std.)
2. LAMINATE MATERIAL : FR4 POLYCLAD 370 or EQUIVALENT
3. COPPER WEIGHT : 1oz START INTERNAL 1/2oz START EXTERNAL
4. FINISHED BOARD THICKNESS : .069 +/- 10%
5. MAXIMUM WARP AND TWIST TO BE : .005 INCH PER INCH
6. MINIMUM COPPER WALL THICKNESS OF PLATED-THRU HOLES TO BE : .001 INCH THERE MUST BE 1MIL OR GREATER PLATING ON EACH SIDE OF THE BARREL WHEN VIEWED IN THE CROSS SECTION
7. MINIMUM ANNULAR RING OF PLATED-THRU HOLES TO BE : .002 INCH
8. MAXIMUM ALLOWABLE LINE REDUCTION TO BE 20% OR .002 WHICHEVER IS SMALLER
9. 6.005 SIGNAL LINES ON LAYER 1 & 6 TO BE IMPEDANCE CONTROLLED 100 OHMS DIFFERENTIAL +/- 10%
10. 0.110 SIGNAL LINES ON LAYER 1 & 6 TO BE IMPEDANCE CONTROLLED 50 OHMS +/- 10%
11. TRACE WIDTH CALCULATIONS ARE STARTING VALUES. BOARD SHOP MAY ADJUST TRACE WIDTHS TO COMPENSATE FOR PROCESS.
12. DIELECTRIC CONSTANTS ARE CORE : 4.1 PREPREG : 4.1

14. A CROSS SECTION MOUNT AND DIGITAL PHOTO'S OF VIA'S TO BE PROVIDED
15. THEIVING IS ALLOWED

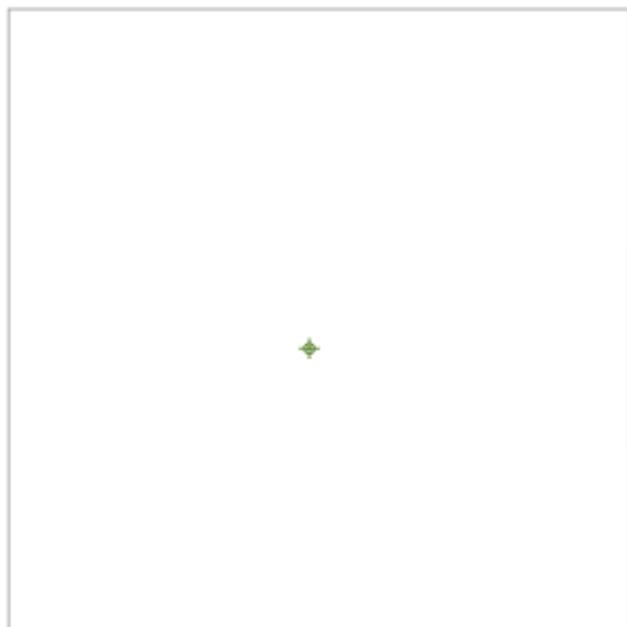
PROCESS NOTES

1. CIRCUITRY ON OUTER LAYERS TO BE PLATED WITH : ENIG
 3. SOLDERMASK BOTH SIDES PER ARTWORK : GREEN LPI
 4. SILKSCREEN BOTH SIDES PER ARTWORK : COLOR = WHITE
- *** ADD UL-94-VO SYMBOL ON BOTTOM SILKSCREEN ***

DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
□	38.0	+3.0/-3.0	PLATED	9
+	38.0	+0.0/-0.0	PLATED	4
○	28.0	+3.0/-3.0	PLATED	2
◦	17.72	+3.15/-3.15	PLATED	2
•	6.0	+2.0/-6.0	PLATED	293
	43.31	+0.0/-0.0	NON-PLATED	2
^	27.56	+0.0/-3.94	NON-PLATED	1
○	98.43x39.37	+0.0/-0.0	PLATED	2
◦	62.99x19.69	+3.15/-3.15	PLATED	2
◦	59.06x19.69	+3.15/-3.15	PLATED	2
◦	41.54x15.75	+3.15/-3.15	PLATED	2
◦	29.53x15.75	+3.15/-3.15	PLATED	2
◦	39.37x23.62	+0.0/-3.94	NON-PLATED	1



	BOARD NAME: 2522DFPDONGLE	BOARD REV: 1.0	KSID: 15428	JOB NUMBER: 124636
	ALL ARTWORK LAYERS VIEWED FROM TOP		LAYER DESCRIPTION: LAYER 13 - FAB	



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